INTEGRATED CIRCUITS

DATA SHEET

hitag

HT1DC20S30 HITAG 1 stick transponder

Product specification Supersedes data of 2000 Apr 19 File under Integrated Circuits, IC11 2001 Sep 24





HITAG 1 stick transponder

HT1DC20S30

FEATURES

- Complete identification transponder for use in contactless applications
- · Operating frequency 125 kHz
- Data transmission and supply energy via RF link, no internal battery
- Low power EEPROM technology for writing distance that equals reading distance
- Total memory size 2048 bits
- · Parts of memory can be write protected by the user
- Effective communication protocol with outstanding data integrity check
- Secure mutual authentication function
- · Encrypted data transmission
- Anticollision protocol for handling of multiple transponders inside the field of the reader antenna
- · Special features:
 - User defined write protection
 - Unique 32-bit serial number for each transponder
 - Encrypted data transmission possible.

GENERAL DESCRIPTION

The HITAG⁽¹⁾ stick transponder HT1DC20S30, based on the HITAG tag IC, is a high performance transponder for bi-directional data transmission in full-duplex mode. Data is stored in the transponder in a non-volatile memory (EEPROM).

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The transponder acts as a passive device, thus not having the need for any internal power supply (battery).

It derives power from the magnetic component of the RF resonant frequency generated by the reader. Data is transmitted by modulating this resonant frequency.

The HT1DC20S30 is dedicated for use in secure access systems where the transponder and the reader have to identify each other.

The EEPROM has a capacity of 2048 bits and is organised in 64 pages. Access is provided either in page mode or in block mode, where 1 block includes 4 pages.

Data transmission from the HT1DC20S30 to the reader uses Manchester or biphase coding and Amplitude Shift Keying (ASK) modulation. Absorption modulation is used to transmit data from the transponder to the reader. The transponder absorbs the magnetic field which hence modulates the current in the reader antenna.

Data transmission from the reader to the HT1DC20S30 uses Binary Pulse Length Modulation (BPLM).

The anticollision feature of the transponder allows to operate several transponders simultaneously in the field of the reader antenna. To use that feature, the reader needs to have implemented the anticollision protocol and must be able to detect bit-collisions (e.g. the Philips HTRM800 long range reader module includes the anticollision protocol.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
f_0	resonant frequency	120	125	130	kHz
f _{trans}	data transfer rate				
	transponder to reader	_	4.0	_	kbits/s
	reader to transponder		5.2	_	kbits/s
М	memory				
	size	_	2048	_	bits
	organization	_	64	_	pages
N	encrypted mutual authentication bits				
	serial number	_	32	_	bits
	secret key		32	_	bits

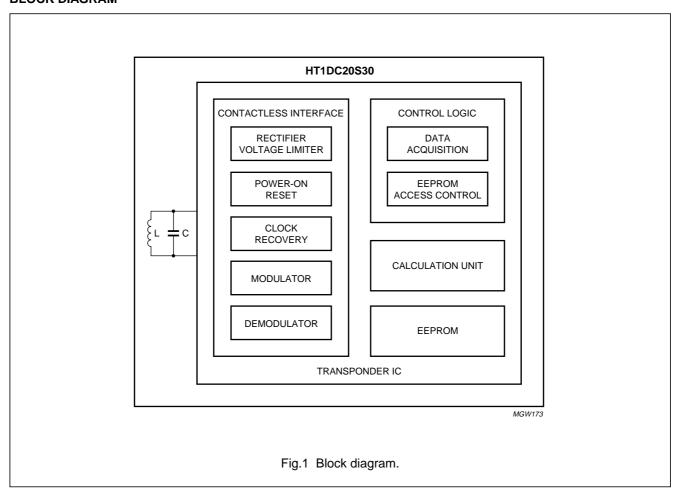
HITAG 1 stick transponder

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ORDERING INFORMATION

TYPE NUMBER		PACKAGE			
I THE NOWIDER	NAME	DESCRIPTION	VERSION		
HT1DC20S30	PLLMC	plastic leadless module carrier	SOT385-1		

BLOCK DIAGRAM



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FUNCTIONAL DESCRIPTION

Related documents

For additional information on the functional description of the HT1DC20S30, in particular the protocol between reader and transponder please refer to the document "HT1 Transponder Family Communication Protocol Reader -HITAG 1 Transponder" (document number HT038522).

Write command - safety instructions

When writing to page 1 (configuration page) we strongly recommend to carefully follow the instructions in the document "HT1 Transponder Family Communication Protocol Reader - HITAG 1 Transponder". In particular, overwriting the reserved bits in configuration page 1 may lead to reduced reading range of the HT1DC20S30.

LIMITING VALUES

All values are in accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS		MAX.	UNIT
N	number of erase/write cycles of EEPROM	T _{amb} = 22 °C	100000	_	
t _{D(ret)}	data retention time of EEPROM	T _{amb} = 55 °C	10	_	years
T _{oper}	operating temperature		-40	+85	°C
T _{stg}	storage temperature		-55	+125	°C
В	magnetic flux density	note 1	_	0.2	Т
a _v	vibration acceleration	10 to 2000 Hz; 3 axis; IEC 68-2-6; Test Fc	_	10	g
as	shock acceleration	3 axis; IEC 68-2-27; Test Ea	_	1500	g

Note

1. Resistivity against magnetic pulses.

ELECTRICAL CHARACTERISTICS

Period time $T_0 = 8 \mu s$ ($f_0 = 125 \text{ kHz}$); note 1.

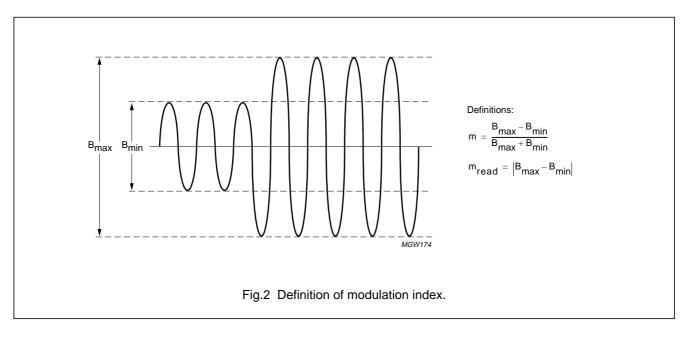
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
f_0	resonant frequency		120	125	130	kHz
В	bandwidth		2.3	_	_	kHz
B _{THR(p-p)}	magnetic flux density for data transmission from transponder (peak-to-peak value)	f ₀ = 125 kHz	50	_	400 ⁽²⁾	μТ
B _{PRG(p-p)}	magnetic flux density for programming the EEPROM (peak-to-peak value)	$f_0 = 125 \text{ kHz}; m = 0.95;$ $t_{LOW} = 8T_0$	50	_	400 ⁽²⁾	μТ
B _{AUTH(p-p)}	magnetic flux density for mutual authentication (peak-to-peak value)	$f_0 = 125 \text{ kHz}; m = 0.95;$ $t_{LOW} = 8T_0$	50	_	400 ⁽²⁾	μТ
B _{READ(p-p)}	field absorption due to the modulation of the transponder (peak-to-peak value)	$f_0 = 125 \text{ kHz};$ $B_{\text{field}} = 50 \mu\text{T (p-p)}$	8	_	_	μТ
MI _{PRG}	modulation index (m) of the base station for programming and authentication	$ f_0 = 125 \text{ kHz;} \\ B_{\text{field}} = 50 \ \mu\text{T (p-p);} \\ t_{\text{LOW}} = 8 \ T_0; \text{ see Fig.2} $	95	_	100	%

Notes

- All parameters are characterized with the SCEMTEC test equipment (STM-1) available from SCEMTEC, Reichshof-Wenrath, Germany. All parameters are guaranteed within the temperature range of T_{amb} = -40 to +85 °C.
- 2. Maximum available field strength of the test equipment. Transponder limit has not been characterized.

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MECHANICAL CHARACTERISTICS

The transponder is sealed in epoxy resin moulding compound. The designation of the package is SOT385-1 (see Chapter "Package outline").

PARAMETER	VALUE
Mechanical dimensions	$12 \times 6 \times 3 \text{ mm}$
Protection class	IP67
Casting material	epoxy resin
Transponder IC type	HT1ICS30

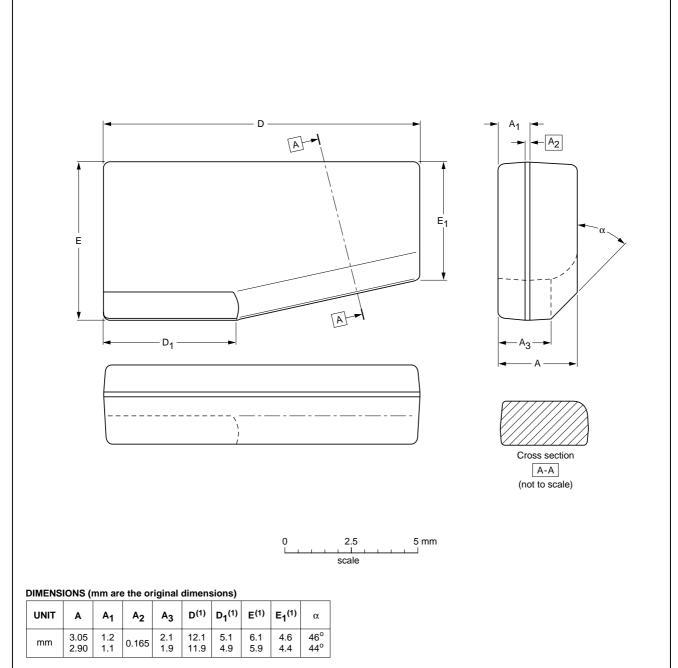
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PACKAGE OUTLINE

PLLMC: plastic leadless module carrier

SOT385-1



Note

1. Plastic protrusions of 0.2 mm per side are not included.

OUTLINE	REFERENCES			EUROPEAN ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT385-1						01-06-27

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DATA SHEET STATUS

DATA SHEET STATUS(1)	PRODUCT STATUS ⁽²⁾	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Notes

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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

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